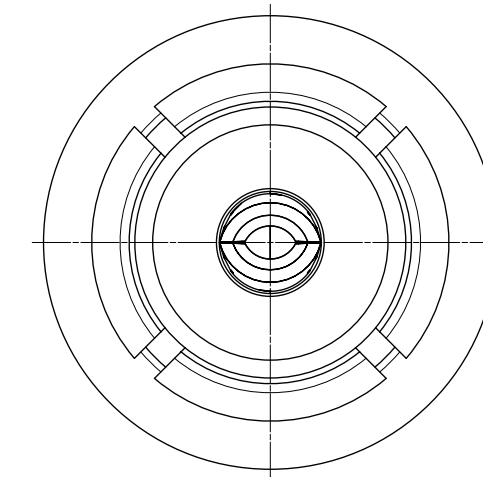
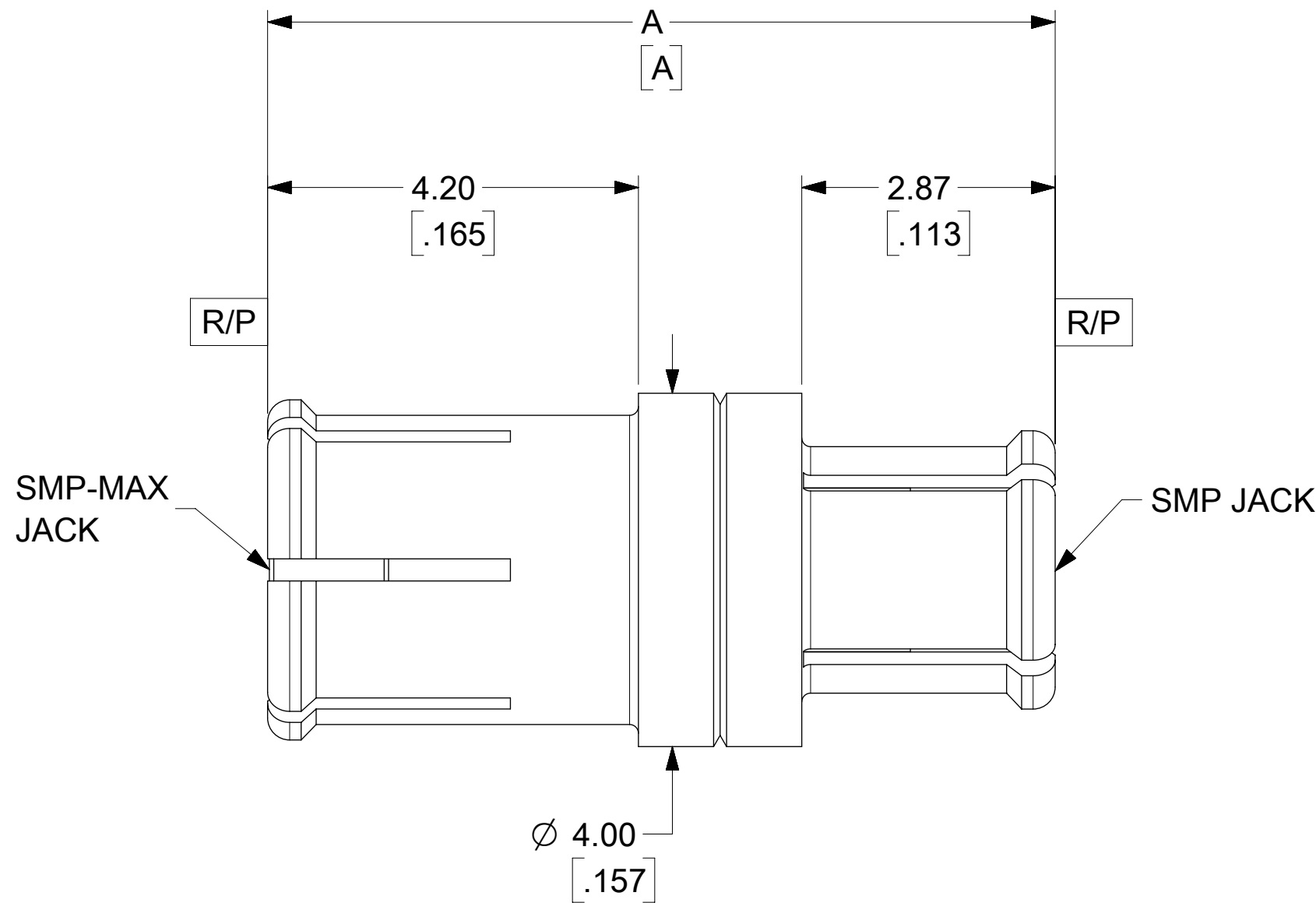
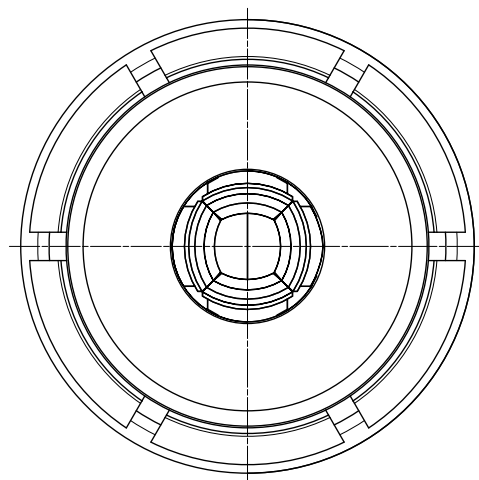
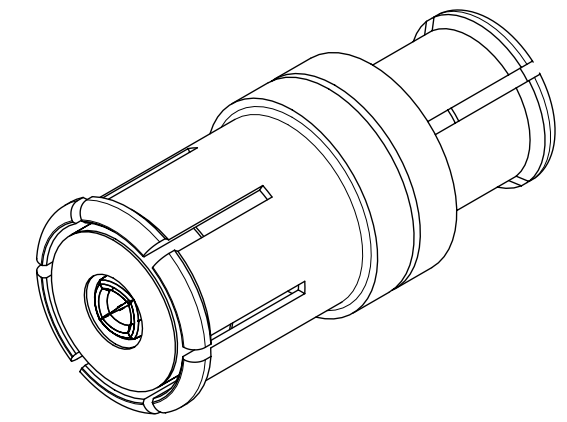


MATERIALS AND FINISHES:

BODY: BERYLLIUM COPPER
 PLATED GOLD (SEE TABLE)
 OVER NICKEL PHOSPHOR (80 MICRO-IN MIN)
 OVER COPPER (20 MICRO-IN MIN)

CONTACT: BERYLLIUM COPPER
 PLATED GOLD (8 MICRO-IN MIN)
 OVER NICKEL PHOSPHOR (80 MICRO-IN MIN)
 OVER COPPER (20 MICRO-IN MIN)

INSULATORS: TEFLON



73420-0014	19.59/.771	1-3 MICRO-IN	TRAY
73420-0013	22.20/.874	8 MICRO-IN MIN	TRAY
73420-0012	19.10/.752	8 MICRO-IN MIN	TRAY
73420-0011	12.60/.496	8 MICRO-IN MIN	TRAY
73420-0010	8.92/.351	8 MICRO-IN MIN	TRAY
PART NO.	DIM A (MM/IN)	BODY	PACKAGING

PS-89675-3760	ELEC/MECH PERFORMANCE
SPECIFICATION	DESCRIPTION

FUNCTIONAL SYMBOLS	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		CURRENT REV DESC: EWR-14619-A UPADTE PART NO TO -0013 FROM -0113		molex		
	DIMENSION UNITS	SCALE					
$\frac{F}{A} = 0$	MM/INCH	NTS	EC NO: 667363		BSA SMP-MAX JACK TO SMP JACK BULLET SMPMAX-BSA, EWR-4353		
$\frac{E}{C} = 0$	GENERAL TOLERANCES (UNLESS SPECIFIED)		DRWN: JSU18 2021/06/17				
$\frac{E}{P} = 0$	ANGULAR TOL ± °		CHK'D: YCHENG 2021/06/18		PRODUCT CUSTOMER DRAWING		
DIVISIONAL SYMBOLS	4 PLACES ±		APPR: YCHENG 2021/06/18				
	3 PLACES ±		INITIAL REVISION:		DOCUMENT NUMBER		
	2 PLACES ±		DRWN: RYEH 2016/09/02				
	1 PLACE ±		APPR: YCHENG 2016/09/05		DOC TYPE		
	0 PLACES ±		THIRD ANGLE PROJECTION				
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		DRAWING		REVISION		
			C-SIZE				
					MATERIAL NUMBER		
					SHEET NUMBER		
					1 OF 1		